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For Immediate Release

Banpil Photonics, Inc. Issued Additional On-Chip Interconnects Patent

SANTA CLARA, California – May 15, 2015 - Banpil Photonics, Inc., a leading company expanding the boundaries of optics and electronics through innovations, today announced that the US Patent Office has issued it an additional patent for on-chip interconnects. The latest patent increases the total number to 27 in the company's overall interconnects patent portfolio, which includes both optical and electrical interconnects, making up its power-efficient, high-speed interconnect platform technology for high performance computing and communications applications.

The Banpil Interconnect IP portfolio, which encapsulates its high-speed interconnects platform technology, is by far the most advanced available in the industry today. It addresses the limits of traditional electrical chip-to-chip interconnects, solves the bottleneck in signal conversion between optics and electrical components to accommodate both in current and future high-speed systems requirements with optical interconnects, and now with the new innovation brings those benefits to on-chip interconnects, which face limits in performance with increasing IC integration.

In current and future IT environments, the demand for higher speeds (also referred to as high-bandwidth) from the smallest devices to computing systems up to global networks, are driven by the increasing higher level of integration within electrical integrated circuits (ICs), with corresponding increases in pin connections per IC, soon to exceed 10,000 interconnections, and higher densities for off-chip interconnections, all demanding novel approaches to be sustainable. More frequently, optical input/output (I/O) is being used in IT systems to transmit data between system components as it is able to attain higher system bandwidth with lower data losses than conventional I/O methods.

"We are proud to achieve this milestone in our Interconnects IP portfolio. We have already demonstrated the significant performance enhancements and benefits to customers that our Interconnects are capable of providing," said Dr. Achyut Dutta, Banpil's CEO. "The patent addition to our portfolio will allow us to more readily work with other technology companies in joint R&D to develop next generation applications or to license our patent portfolio for their own application product development." Banpil has made sample-level products available for demonstration. The company welcomes opportunities to work with system vendors to explore new or enhanced applications, technology licensing, strategic manufacturing partnerships as well as investors.

About Banpil Photonics, Inc.

Banpil Photonics is expanding the boundaries of optics and electronics through innovations. Banpil develops and manufactures next generation multispectral image sensors for automotive & medical imaging systems, security & surveillance, and machine vision applications; high-efficiency energy harvesting devices for energy applications; and low-power, high-speed electrical interconnects for chip-to-chip, chip-to-board, board-to-board, and rack-to-rack applications in high performance computing and networking. The company has an extensive IP portfolio of these innovations available for licensing. For more information, visit www.banpil.com.

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